

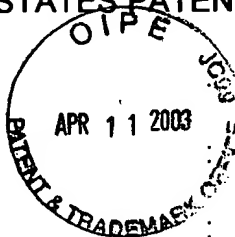
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuhiro NOBORI et al.

Serial No. 09/722,737

Filed November 28, 2000



Confirmation No. 5253

Docket No. 2000-1645A

Group Art Unit 2822

Examiner K. Rose

4-17/15
4/18/03

SEMICONDUCTOR PACKAGE AND METHOD FOR FORMING SEMICONDUCTOR PACKAGE

AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

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Responsive to the Office Action mailed December 19, 2002, the time for responding thereto being extended for one month in accordance with a Petition for Extension submitted herewith, please amend the above-identified application as follows:

IN THE DRAWINGS:

A proposed new Figure 19, as shown in red on the attached sheet has been filed.

IN THE SUBSTITUTE SPECIFICATION:

Please replace paragraph [0013] on page 3, with the following rewritten paragraph:

In accomplishing these and other aspects, according to a first aspect of the present invention, there is provided a semiconductor package comprising:

a first semiconductor having electrodes formed on both of an upper and a lower face;

a heat radiating plate to which a lower face electrode of the first semiconductor is joined with use of a joining member; and

UE